221 These assemblies are ESD sensitive, ESD precautions shall be observed.
222 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
223 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
224 Install 'C8' bent over horizontally & apply RTV167 to secure to the PCB surface, bend radius should follow best practice guidelines.
225 'C8' is a non-IPC compliant, custom footprint

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

<table>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: PMP6023-1</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<td>IGNORE: Top Overlay</td>
<td>GENERATED: 8/14/2014 1:03:03 PM</td>
<td>TEXAS INSTRUMENTS</td>
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COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANTS: [No Variations]

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<th>PCB VIEWED FROM BOTTOM SIDE</th>
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